

010204  
14461 U.S.PTO

PATENT APPLICATION  
Docket No. 9903-074  
Client No. S03US003

16018 U.S.PTO  
10/750979  
010204

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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I HEREBY CERTIFY THAT THIS PAPER AND ENCLOSURES AND/OR FEE ARE BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE "EXPRESS MAIL POST OFFICE TO ADDRESSEE" SERVICE UNDER 37 CFR 1.10 ON THE DATE INDICATED ABOVE AND IS ADDRESSED TO: MAIL STOP PATENT APPLICATION, COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450.

HILLARY A. DIXON  
(SENDER'S PRINTED NAME)

Hillary A. Dixon  
(SIGNATURE)

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Enclosed for filing is a patent application under 37 CFR 1.53(b) of:

Inventor(s): Dong-Ho Lee

For: STACK PACKAGE MADE OF CHIP SCALE PACKAGES

Applicant requests FIG. 4 to be published with the application.

Enclosures:

- Specification (pages 1-6); claims (pages 7-10); abstract (page 11)  
 THREE sheet(s) of FORMAL drawings (comprising 6 figures)  
 Combined Declaration and Power of Attorney (unsigned)  
 Assignment with cover sheet  
Assignee Name and Address: Samsung Electronics Co., Ltd.  
Suwon-city, Kyungki-do Republic of Korea  
 PTO 1449 Information Disclosure Statement with 6 cited references

CLAIMS AS FILED

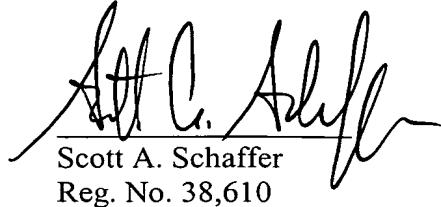
For	Number Filed	Number Extra	Rate	Basic Fee \$770
Total Claims	20-20	0	x \$ 18 =	\$0.00
Independent Claims	2-3	0	x \$ 86 =	\$0.00
TOTAL FILING FEE				\$770.00

- Certified copy of Korean Priority Document No. 2003-0281, filed January 3, 2003, from which priority is claimed.
- Return Postcard

**Customer No. 20575**

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.



A handwritten signature in black ink, appearing to read "Scott A. Schaffer".

Scott A. Schaffer  
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